Title (en)

METHOD AND APPARATUS FOR IMPROVED CHEMICAL MECHANICAL PLANARIZATION

Title (de)

VERFAHREN UND VORRICHTUNG ZUR VERBESSERTEN CHEMISCH-MECHANISCHEN PLANARISIERUNG

Title (fr)

PROCEDE ET APPAREIL DE PLANARISATION CHIMICO-MECANIQUE

Publication

**EP 1799402 A4 20091216 (EN)**

Application

**EP 05808056 A 20051005**

Priority

- US 2005035979 W 20051005
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- US 63925704 P 20041227

Abstract (en)

[origin: WO2006042010A1] A polishing pad includes a guide plate having affixed thereto a porous slurry distribution layer on one side and a flexible under-layer on the other side. A plurality of polishing elements interdigitated with one another through the slurry distribution layer and the guide plate so as to be maintained in planar orientation with respect to one other and the guide plate are affixed to the flexible under-layer and each polishing element protrudes above the surface of the guide plate to which the slurry distribution layer is adjacent. Optionally, a membrane may be positioned between the guide plate and the slurry distribution layer. The polishing pad may also include wear sensors to assist in determinations of pad wear and end-of-life.

IPC 8 full level

**B24B 37/26** (2012.01); **B24D 11/00** (2006.01)

CPC (source: EP KR)

**B24B 37/26** (2013.01 - EP); **B24D 11/00** (2013.01 - KR)

Citation (search report)

- No further relevant documents disclosed
- See references of WO 2006042010A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

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